SUSS MICROTEC INVESTOR PRESENTATION

September 2013

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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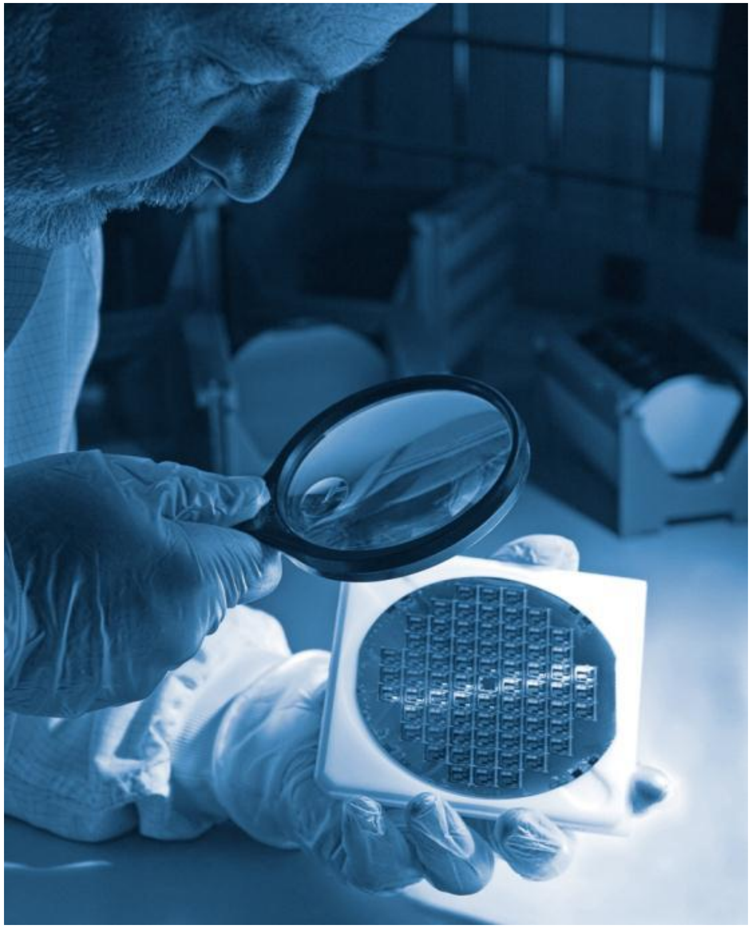
SUSS MICROTEC AT A GLANCE

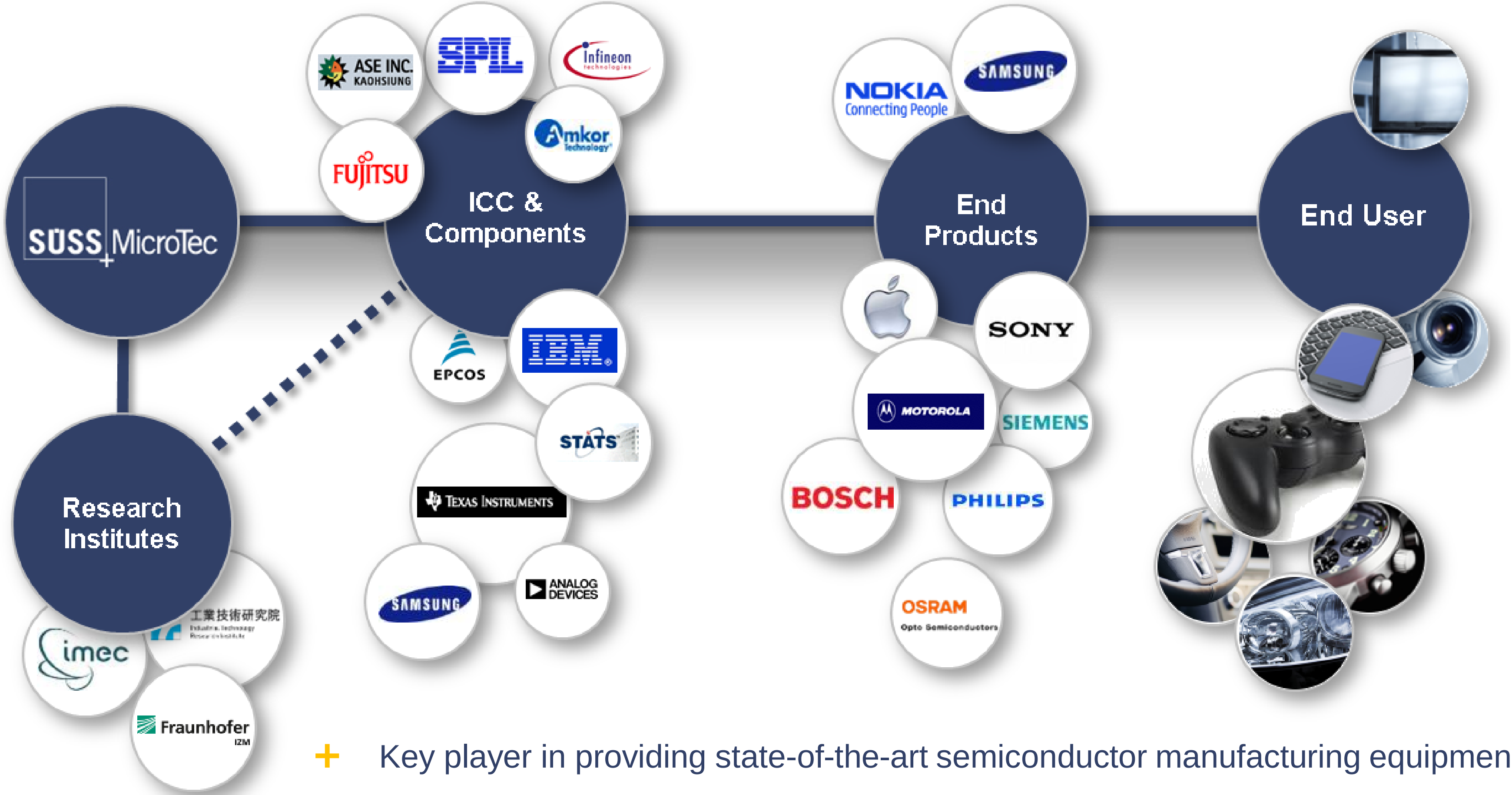
- SUSS MicroTec: A global leader in semiconductor equipment
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- We are focused on high growth market segments: Semiconductors, MEMS, LEDs



- Key Data:
  - Stock Exchange Symbol: SMHN
  - TecDAX
  - Share price*: 7.23 €
  - Market Cap*: 138 € million
  - Net Cash, June 30, 2013: 19.5 € million

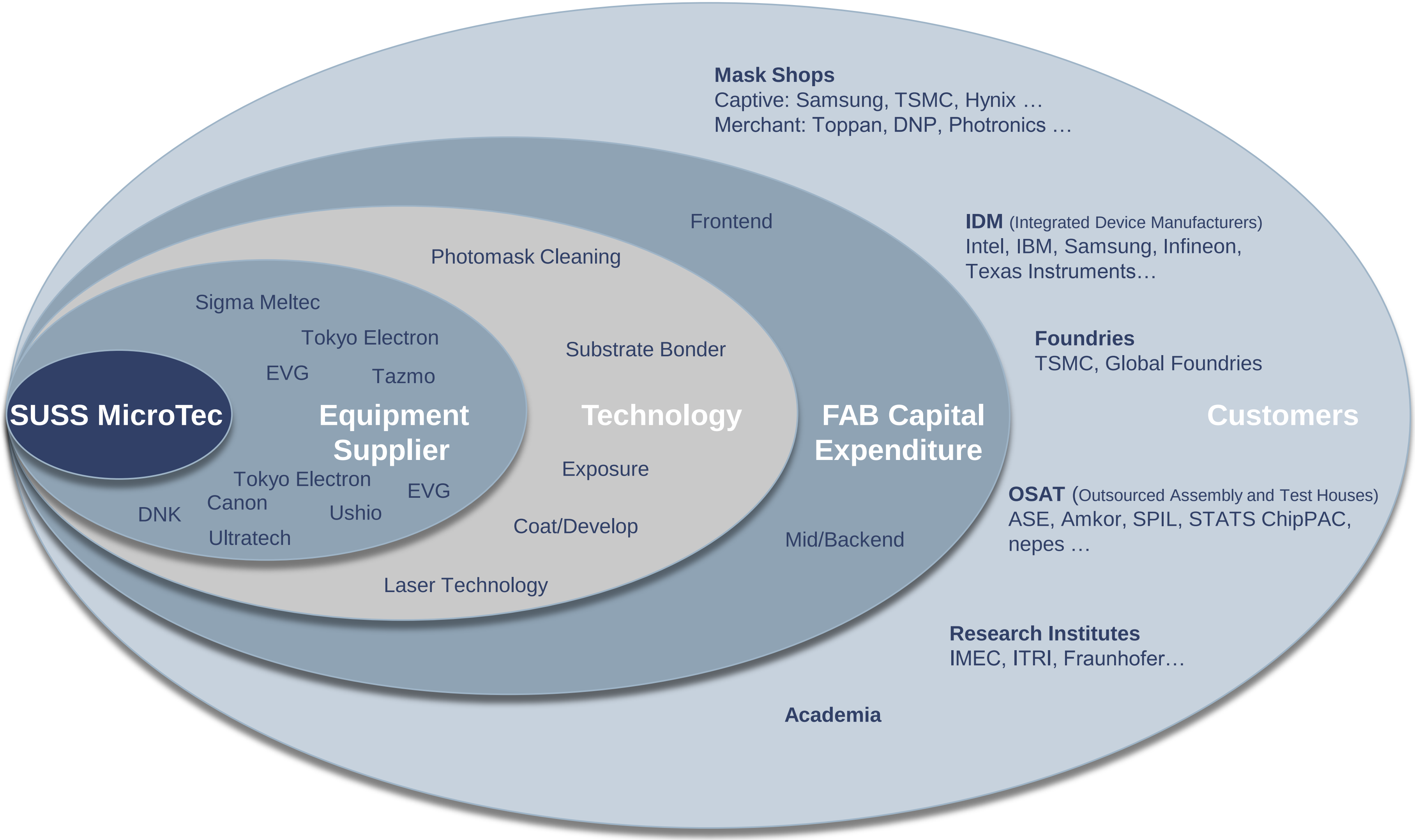
* July 31, 2013

SUSS MICROTEC IN THE VALUE CHAIN



- Key player in providing state-of-the-art semiconductor manufacturing equipment
- Development of highly innovative process solutions with industry and R&D partners
- Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

THE SEMICONDUCTOR MARKET



Mask Shops
Captive: Samsung, TSMC, Hynix …
Merchant: Toppan, DNP, Photronics …

IDM (Integrated Device Manufacturers)
Intel, IBM, Samsung, Infineon, Texas Instruments…

Foundries
TSMC, Global Foundries

Customers

OSAT (Outsourced Assembly and Test Houses)
ASE, Amkor, SPIL, STATS ChipPAC, nepes …

Research Institutes
IMEC, ITRI, Fraunhofer…

Academia

FAB Capital Expenditure

Frontend

Mid/Backend

Technology

Photomask Cleaning

Substrate Bonder

Exposure

Coat/Develop

Laser Technology

Equipment Supplier

Sigma Meltec

Tokyo Electron

EVG

Tazmo

Tokyo Electron

Canon

EVG

DNK

Ushio

Ultratech

SUSS MicroTec

SUSS MICROTEC – A GLOBAL PLAYER

🟦 Sunnyvale, US
▨ Corona, US

■ ▨ Garching, DE
▨ Sternenfels, DE
▨ Hâuterive, CH
🟦 Lyon, FR
🟦 Coventry, UK

Singapore, SG 🟦

🟦 Shanghai, CN
🟦 Hsin Chu, TW

🟦 Yokohama, JP
🟦 Hwaseong City, KR

■ Headquarters
▨ Production
🟦 Sales

MAIN PRODUCTION SITES

Germany

Garching

- SUSS MicroTec HQ
- Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
- Core competencies:
  - **Exposure** (proximity exposure)
  - **Alignment**

Sternenfels

- Development/production :
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
- Core competencies:
  - **Wet processing**
  - **Wafer bonding**

USA

Corona

- Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
- Core competencies:
  - **Exposure** (UV projection lithography)
  - **Laser Ablation**

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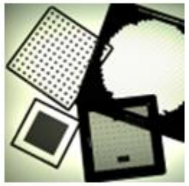
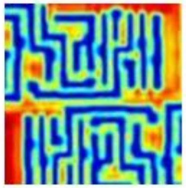
KEY MARKETS

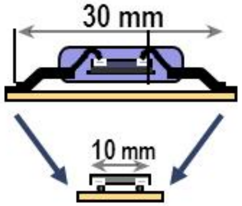
Semiconductors

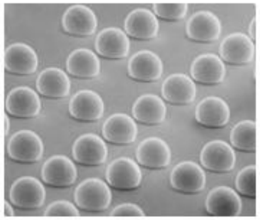
Mask Manufacturing
Photomask Cleaning



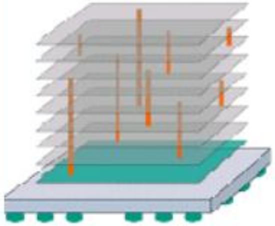


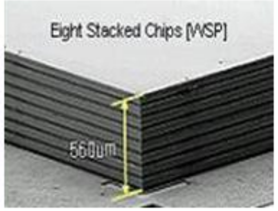
Advanced Packaging
Micro-Bumping





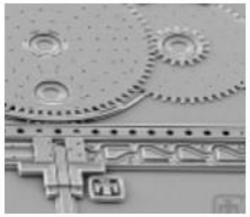
3D Integration/Stacking





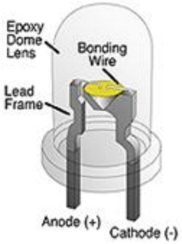
Sensors

MEMS
Computing, Automotive,
Medical Applications …



Lighting

LED
General Lighting,
HB and UHB LED



SEGMENTS, PRODUCTS AND MARKETS

Segments	**Photomask Equipment**	**Lithography**			**Substrate Bonder**
Products	 **MaskTrack Pro**	 **Exposure Systems**		 **Coater/Developer**	 **Wafer Bonder**
	Frontend	**Mid- and Backend**			
Process Steps	**Photomask Cleaning**	**Stepper, Scanner** (UV projection) **Laser Ablation**	**Mask Aligner** (proximity exposure) **Nano Imprinting**	**Coating Developing**	**Bond Alignment** **Permanent Bonding** **Temporary Bonding**
Key figures H1 2013	**Sales: 9.2 € million** **EBIT: -0.2 € million**	**Sales: 37.1 € million** **EBIT: 0.2 € million**			**Sales: 6.6 € million** **EBIT: -14.5 € million**

Markets

- **Mask Manufacturing**
- **Advanced Packaging**
- **3D Integration**
- **MEMS**
- **LED**

STATUS UPDATE : PERMANENT BONDING

- Extraordinary expenses of € 6.0 million, which accrued in connection with the refocusing of the Permanent Bonding
  - Thereof, € 4.6 million value adjustments on capitalized development costs from the years prior to 2008, demonstration equipment, and other inventories
  - Thereof, € 1.4 million provisions for commitments and other agreements
- One-off effect was € 0.8 million lower than originally expected, because of lower valuation adjustments on demonstration equipment

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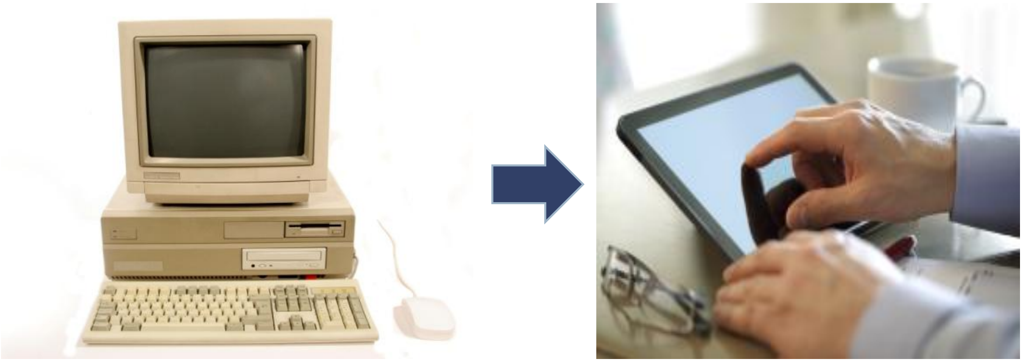
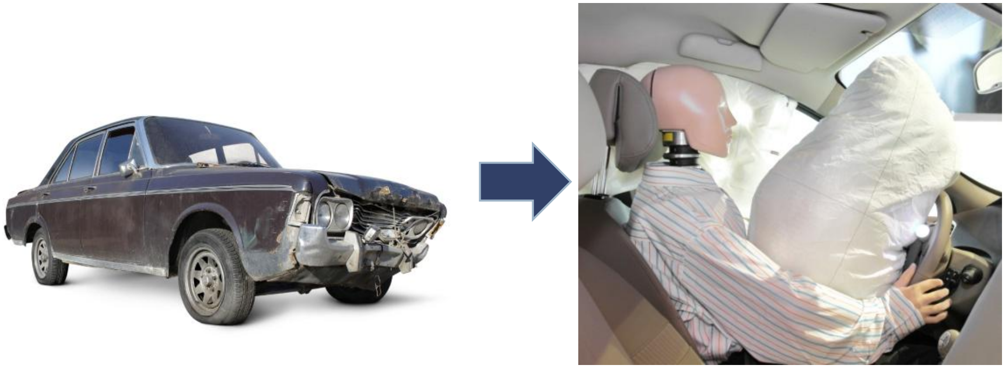
TECHNOLOGY EVOLUTION

~1985...today



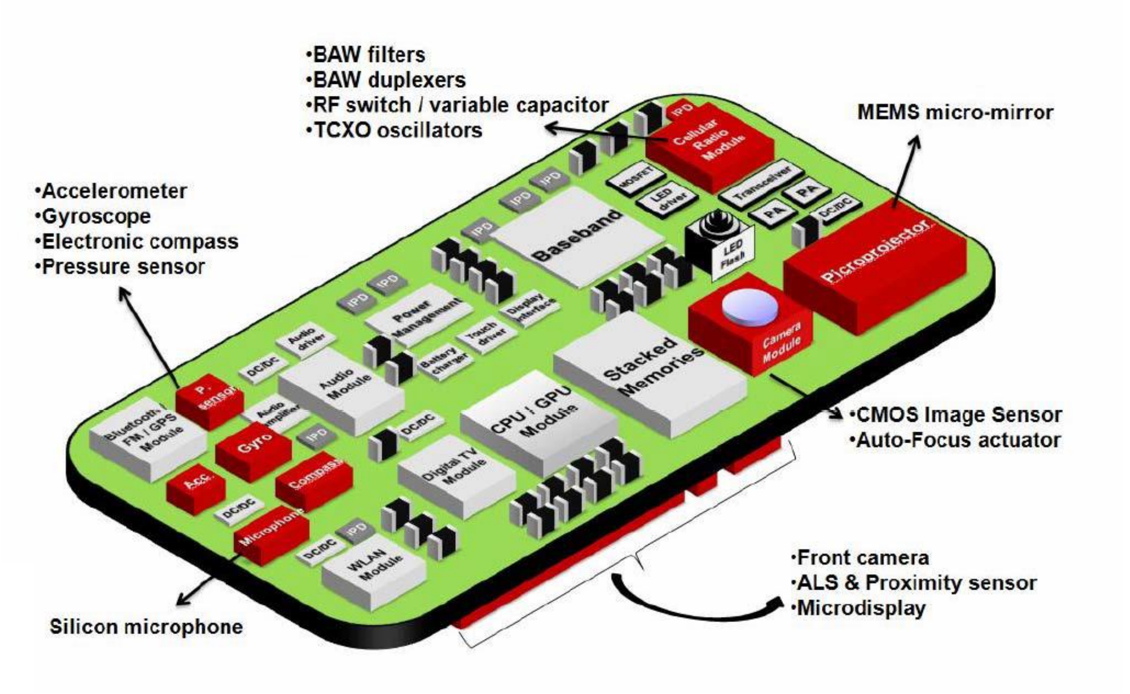
~1987...today

~1910...today



~1950...today

GROWTH DRIVER SMARTPHONES AND TABLETS



- BAW filters
- BAW duplexers
- RF switch / variable capacitor
- TCXO oscillators

MEMS micro-mirror

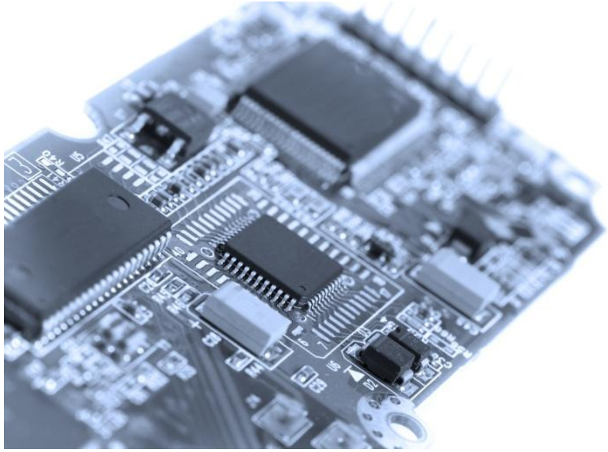
- Accelerometer
- Gyroscope
- Electronic compass
- Pressure sensor

- CMOS Image Sensor
- Auto-Focus actuator

- Front camera
- ALS & Proximity sensor
- Microdisplay

Silicon microphone

Source: Yole Developpement



MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality

E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs

Energy Efficiency

- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting
- Energy efficiency in industrial production
- Smart energy management in household applications safes energy

EXPECTED MARKET DEVELOPMENTS

With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:

Advanced Packaging	Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets
3D Integration (TSV)	Transition to production volume in the years to come
Compound Semiconductors	LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

Segment growth 2011 - 2016E CAGR ~ 15% (Gartner and industry estimates)

SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

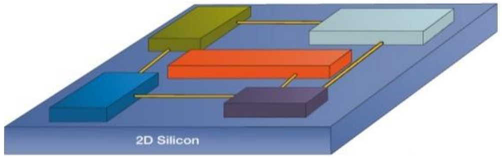
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple pattering allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

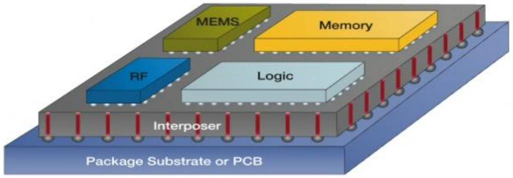
2.5D Packaging

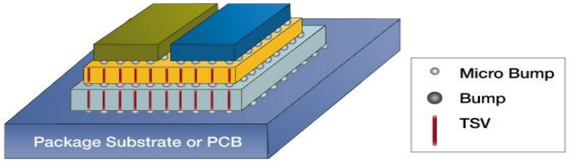
- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law

3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption







SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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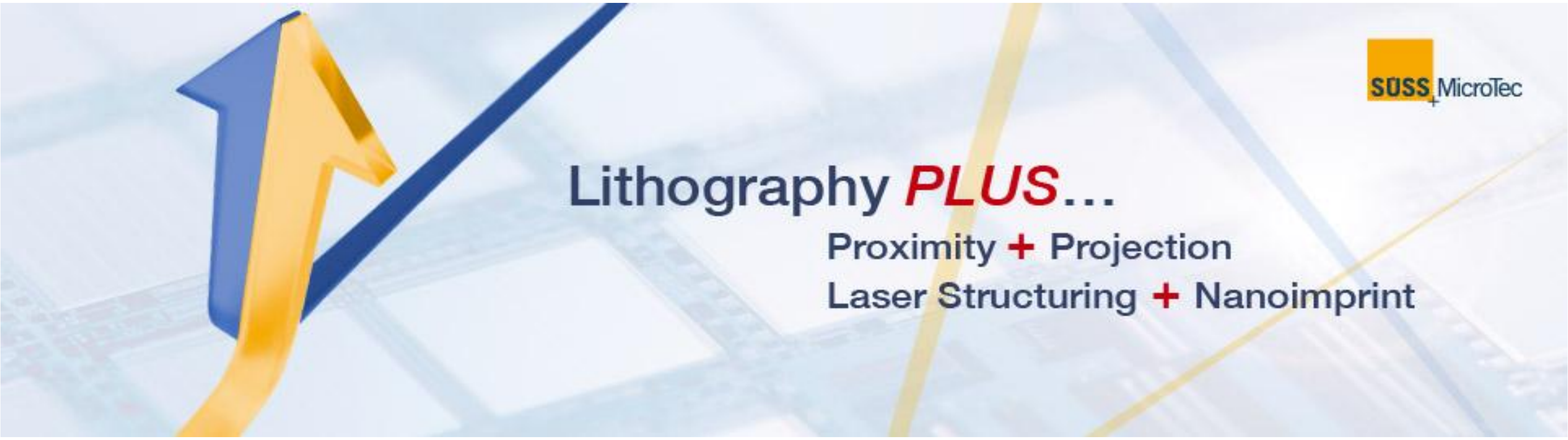
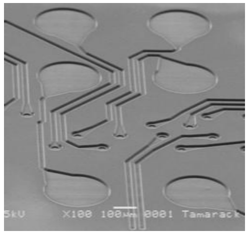
LITHOGRAPHY COMPETENCY

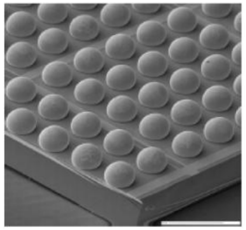
- Increasing chip performance requires the adoption of innovative lithography technologies in the semiconductor backend
- **Not one single exposure technology fits all needs at the same time**
- The newly acquired Stepper/Scanner products supplement our Mask Aligner product line and enlarges our technology portfolio by the key competencies UV-projection lithography and laser ablation
- SUSS MicroOptics S.A. adds key know how for critical lithography performance improvements



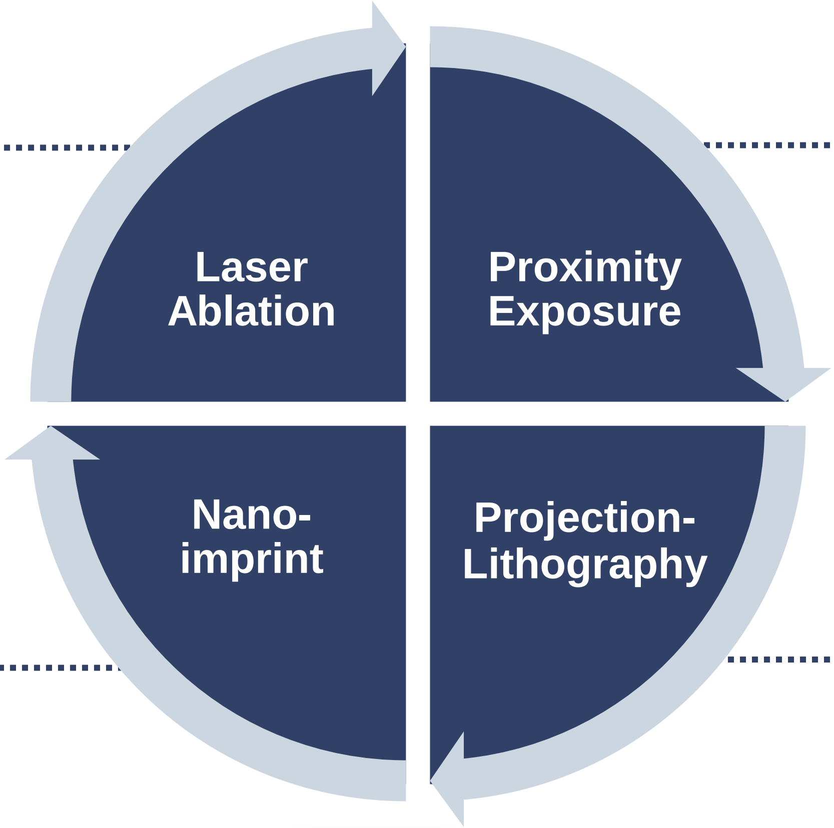
EXPOSURE SOLUTIONS



WLCSP:
Fanout WLP



Flip Chip:
Solder Bumping



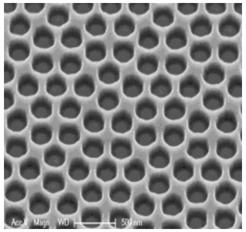
Laser Ablation

Proximity Exposure

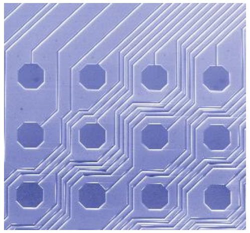
Nano-imprint

Projection-Lithography

LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



+ **Only SUSS MicroTec offers complete exposure solutions for the mid-/back-end**

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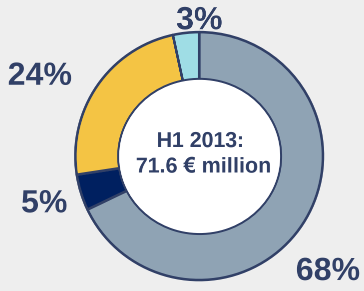
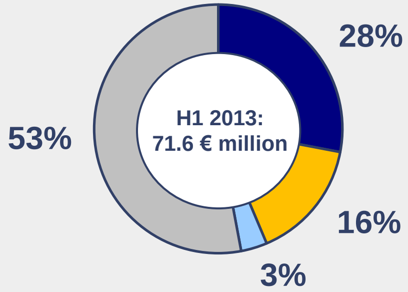
ORDER ENTRY AND SALES BY SEGMENT AND REGION H1 2013

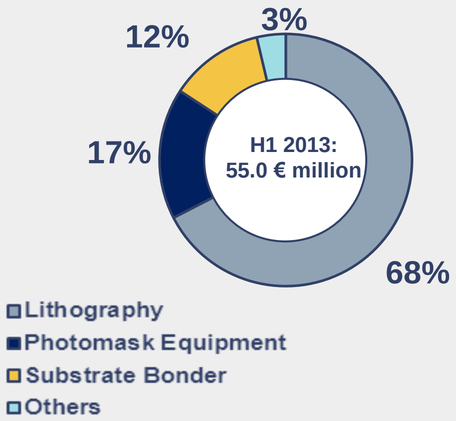
Order Entry by Segment



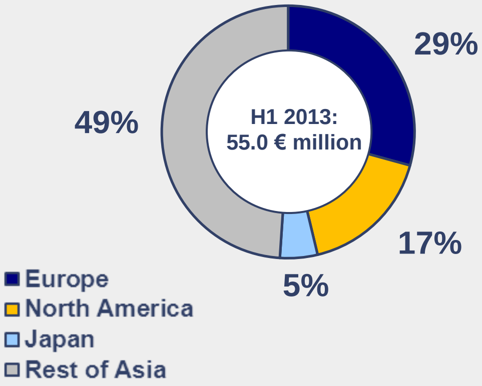
Order Entry by Region



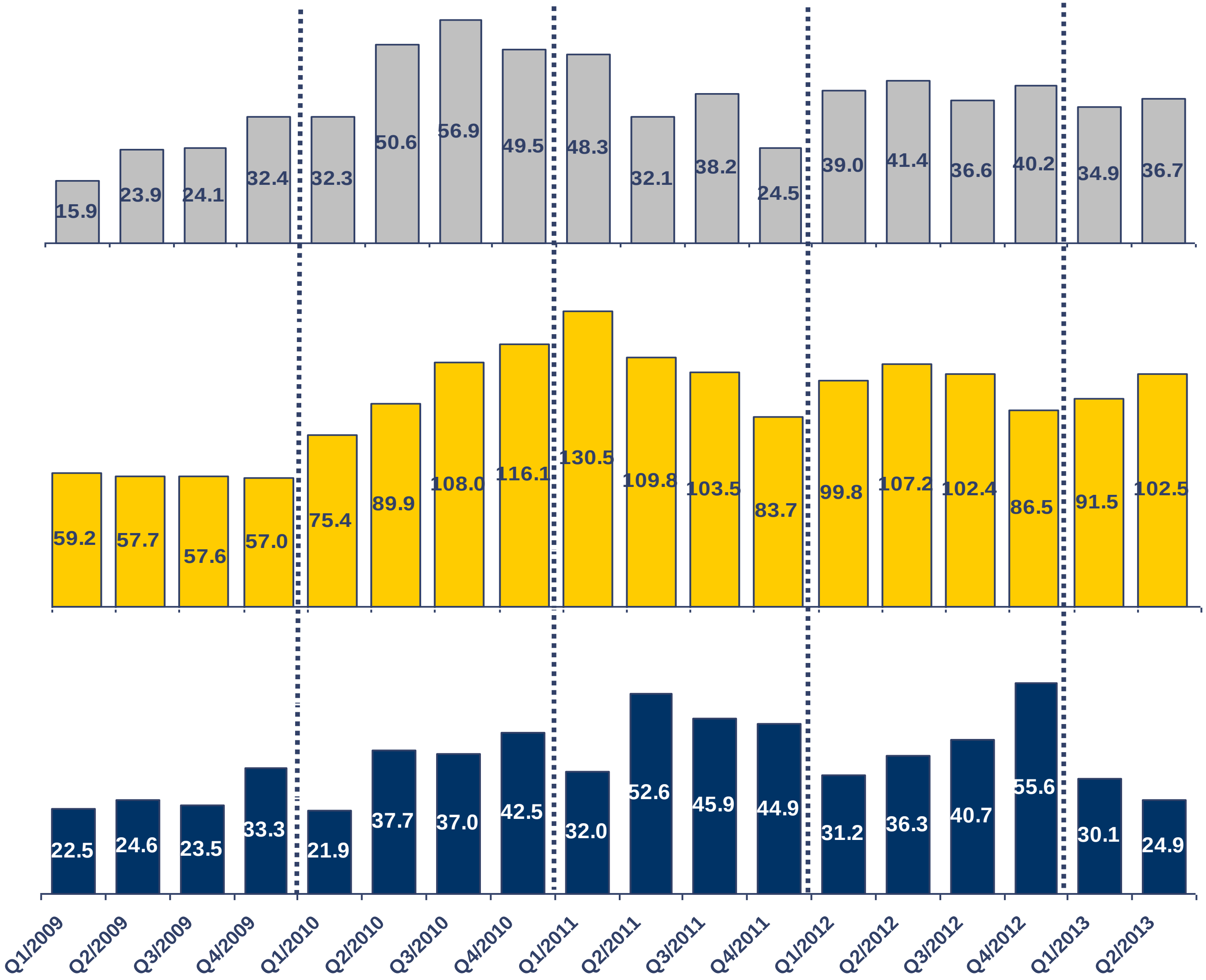
Sales by Segment



Sales by Region



LONG TERM BUSINESS DEVELOPMENT



Order Entry

in € million

2012: € 157.2 million

Order Backlog

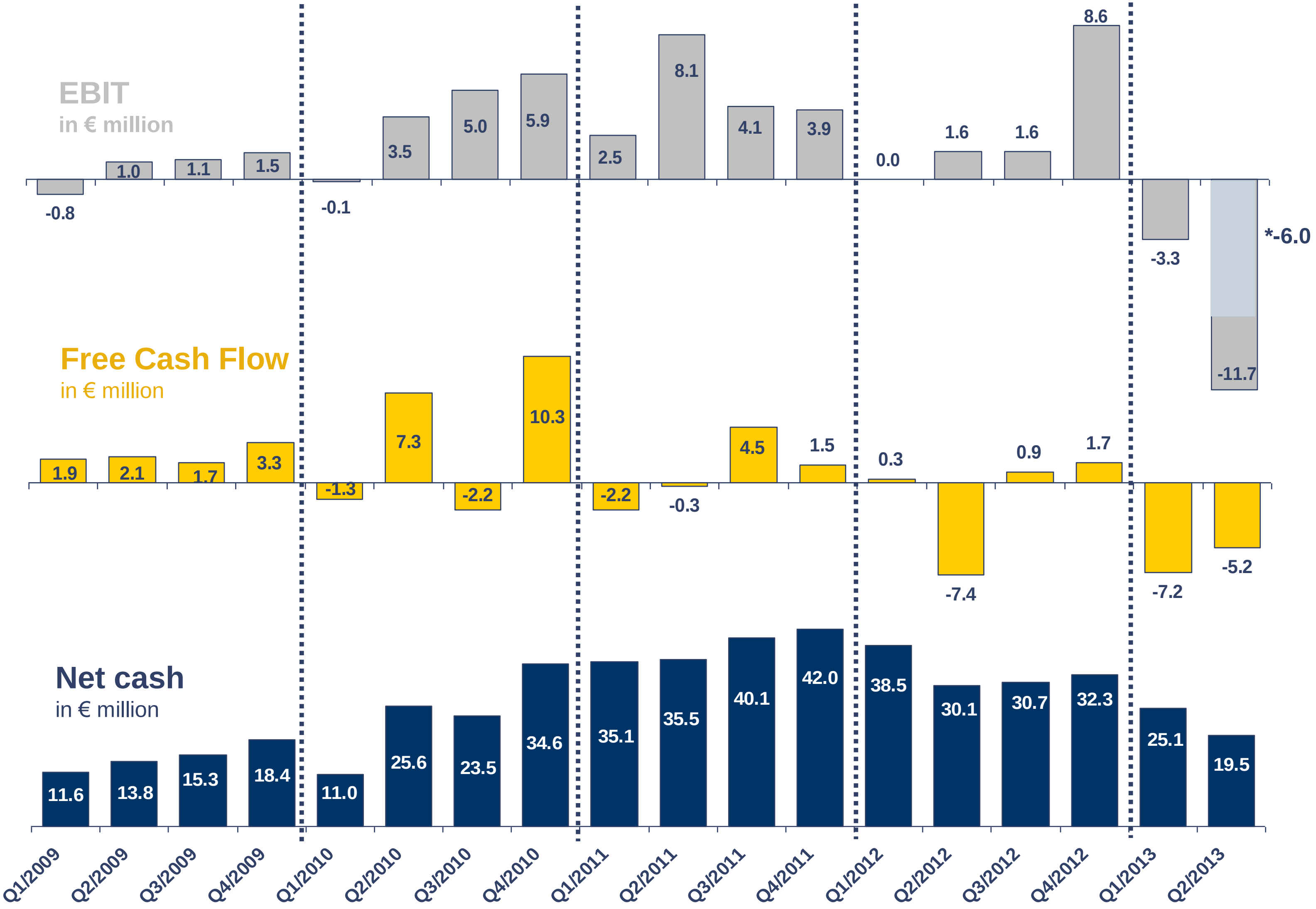
in € million

Sales

in € million

2012: € 163.8 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from refocusing product line permanant bonding

KEY FINANCIALS

in € million	Q2 2013	Q2 2012	in %	*H1 2013*	*H1 2012*
Order Intake	**36.7**	**41.4**	**-11.4%**	***71.6***	***80.4***
Order Backlog 6/30	**102.5**	**107.2**	**-4.4%**	***102.5***	***107.2***
Revenue	**24.9**	**36.3**	**-31.4%**	***55.0***	***67.5***
EBIT	**-11.7**	**1.6**	**--**	***-15.0***	***1.5***
EBIT in % of Sales	*-47,0%*	*4.4%*	--	*-27.3%*	*2.2%*
EBIT (adjusted)	**-5.7**	**1.6**	**--**	***-9.0***	***1.9***
EBIT (adjusted) in % of Sales	*-22.8%*	*4.4%*	--	*-16.4%*	*2.8%*
Earnings after tax (continuing operations)	**-9.1**	**0.6**	**--**	***-11.6***	***0.4***
Earnings after tax	**-9.1**	**0.6**	**--**	***-11.6***	***1.9***
EPS in €	**-0.48**	**0.03**	**--**	***-0.61***	***0.10***
Free Cash Flow*	**-5.2**	**-7.4**	**--**	***-12.4***	***-7.1***
Net Cash**	**--**	**--**	**--**	***19.5***	***30.1***
Employees 6/30	**--**	**--**	**--**	***680***	***689***

* before consideration of purchased interest-bearing securities , the acquisition of Tamarack and the gain out of the sale from the Test Business

** incl. stock of interest-bearing securities

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SUMMARY AND OUTLOOK

2013: - Milestone achievement in temporary bonding
- Refocusing of product line Permanent Bonding
- Further integration of SUSS MicroTec Photonic Systems

Fundamental growth in target markets

Strong competitive positioning: first or second in the target markets

Leading equipment company in the semiconductor backend, enabling “Moore’s Law”as well as “More than Moore”

Outlook

FY 2013: - Sales of approximately 150 € million
- EBIT: minus 10 – minus 15 million €

Q3 2013: - Order Intake 30 - 40 € million

SÜSS MicroTec AG
Schleissheimer Str. 90
85748 Garching

www.SUSS.com

INVESTOR RELATIONS INFORMATION

Contact

Franka Schielke

Tel.: +49 (0) 89-32007- 161
Fax.: +49 (0) 89-32007- 451
Email: franka.schielke@suss.com

SÜSS MicroTec AG
Schleissheimer Strasse 90
85748 Garching (Munich)
Germany
www.suss.com

Financial Calendar 2013

Interim Report 2013	8. Aug.
Commerzbank TMT Conference, Frankfurt	28. Aug
Deutsche Bank Technology Conference, Las Vegas	11.-12. Sep.
Bankhaus Lampe German Technology Seminar, Zurich	13. Sep.
UBS Best of Germany Conference, New York	16. - 18. Sep
Baader Investment Conference, Munich	24. Sep.
Berenberg/Goldman Sachs, German Corporate Conference	25. Sep.
UniCredit/Kepler Investment Conference, Munich	26. Sep.
Nine-month Report 2013	7. Nov.
German Equity Forum, Frankfurt/Main	11. - 13. Nov
Morgan Stanley TMT Conference, Barcelona	21. - 22. Nov

OUR TECHNOLOGY ENABLES SUSTAINABILITY

Equipment

- SUSS MicroTec equipment is designed to efficiently use electricity and chemicals
- ReMan, the remanufacturing operation of SUSS MicroTec takes back used equipment and refurbishes it

Remanufactured by OEM
CERTIFIED

Applications

- 3D IC and chip scaling helps reducing energy and material consumption
- LEDs for efficient lighting solutions
- MEMS applications improve performance of mobile devices and conserve energy
- Shift to renewable energies requires more power devices and high-performance ICs (e.g. for solar and wind power systems)
- Laser Ablation in lieu of photolithography (seed layer removal)

Initiatives

- Partner company of VDMA BlueCompetence initiative, a network of equipment providers in Germany, who are following a sustainable business approach
- Innovative lighting solution in Sternenfels
- Improved climatization system of cleanrooms
- Paperless invoice system

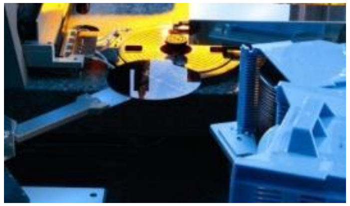
BLUECOMPETENCE
Alliance Member
Partner der Nachhaltigkeitsinitiative
des Maschinen- und Anlagenbaus

SUSS MICROTEC PRODUCT PORTFOLIO

Photomask Equipment

Coater/Developer

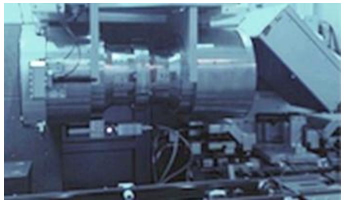
Wafer Bonders



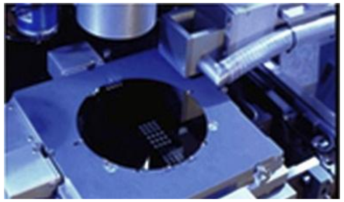
Alignment Verification Systems

Mask Aligners

Imprinting Systems



UV-Projection Stepper / Scanner



Excimer Laser Systems